

ABSTRACT OF THE DISCLOSURE

A system, apparatus and/or method is provided for removing water vapor from a wafer processing chamber generated as a byproduct of wafer processing. A water vapor trap is used to collect the water vapor byproduct from the processing chamber interior. The water vapor trap has at least a portion thereof in communication with an interior of the processing chamber for collection of the water vapor and another portion thereof in communication with an exterior of the processing chamber. The portions are movable with respect to the interior and exterior of the processing chamber such that the portions may switch places. This allows the processing chamber to be in at least a substantially continuous mode of operation while still providing for the removal of water vapor byproduct via the water vapor trap. The "used" portion of the water vapor trap is regenerated while the "clean" portion is collecting water vapor.